In the Claims

Please cancel claims 34-46 and add claims 55-75.

Following is a clean version of the added claims, which represents all of the pending claims.

Clean Version Of Added Claims

55. (added) A method for burn-in testing a semiconductor die having a pad comprising:

providing a test fixture comprising an external lead for establishing electrical contact between the die and a burn-in oven;

providing a plastic film comprising a bump for electrically contacting the pad, and a conductive trace in electrical communication with the bump and the external lead;

placing the die on the test fixture;

placing the bump into electrical contact with the pad; and

placing the external lead in electrical contact with the burn-in oven.

56. (added) The method of claim 55 wherein the test fixture comprises a plurality of external leads and the plastic film comprises a plurality of bumps and a plurality of conductive traces in electrical communication with the bumps.

57. (added) The method of claim 55 wherein the placing the bump step is performed with a compressible member in the test fixture configured to bias the bump against the pad.

58. (added) The method of claim 55 wherein the test fixture comprises a cover and a compressible member on the

cover and the placing the bump step is performed using the compressible member and the cover.

59. (added) The method of claim 55 wherein the placing the bump step is performed by bonding the bump to the pad.

60. (added) The method of claim 55 wherein the pad comprises a bondpad.

61. (added) A method for burn-in testing a semiconductor die having a plurality of pads comprising:

providing a test fixture comprising a compressible member and a plurality of external leads for establishing electrical contact between the die and a burn-in oven;

providing a plastic film comprising a plurality of bumps for electrically contacting the pads, and a plurality of conductive traces in electrical communication with the bumps and the external leads;

placing the die on the test fixture and the plastic film on the die;

biasing the bumps into electrical contact with the pads using the compressible member; and

placing the external leads in electrical contact with the burn-in oven.

62. (added) The method of claim 61 wherein the pads comprise bond pads.

63. (added) The method of claim 61 wherein the plastic film comprises a plurality of second bumps in electrical communication with the conductive traces and configured to establish electrical communication with the external leads.

64. (added) The method of claim 61 wherein the external leads comprise pins in a dual in line (DIP) configuration.

65. (added) The method of claim 61 wherein the external leads comprise pins in a quad flat pack (QFP) configuration.

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66. (added) The method of claim 61 wherein the test fixture comprises a plate for the die, a cover attached to the compressible member and a clip for attaching the cover to the plate.

D2 cont.

67. (added) A method for burn-in testing a semiconductor die having a pad comprising:

providing a test fixture comprising a plate, a contact on the plate, and an external lead on the plate in electrical communication with the contact for establishing electrical contact between the die and a burn-in oven;

providing a die contact member for electrically connecting the pad to the external lead, the member comprising a plastic film, a first bump on the film for electrically contacting the pad, a conductive trace on the film in electrical communication with the first bump, and a second bump on the film in electrical communication with the conductive trace;

placing the die in the test fixture;

placing the first bump in electrical contact with the pad on the die;

placing the second bump in electrical contact with the contact on the plate; and

placing the external lead in electrical contact with the burn-in oven.

68. (added) The method of claim 67 wherein the placing the first bump step comprises biasing the first bump against the pad.

69. (added) The method of claim 67 wherein the placing the first bump step comprises biasing the first bump against the pad using a compressible member on the plate.

70. (added) The method of claim 67 wherein the placing the first bump step comprises bonding the first bump to the pad.

71. (added) The method of claim 67 wherein the placing the first bump step comprises bonding the second bump to the contact.

72. (added) A method for burn-in testing a semiconductor die having a pad comprising:

providing a test fixture comprising an external lead for establishing electrical contact between the die and a burn-in oven;

providing a plastic film comprising a bump for electrically contacting the pad, and a conductive trace in electrical communication with the bump and the external lead;

placing the die on the test fixture;

bonding the bump to the pad; and

placing the external lead in electrical contact with the burn-in oven.

73. (added) The method of claim 72 wherein the test fixture comprises a plurality of external leads and the plastic film comprises a plurality of bumps and a plurality of conductive traces in electrical communication with the bumps.

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74. (added) The method of claim 72 further comprising removing the die from the test fixture with the bump bonded to the pad.

75. (added) The method of claim 72 wherein the plastic film comprises a second bump bonded to the test fixture.